The collaboration between US and Japan in composite materials and structures has been very successful both academically as well as commercially, including recent Boeing-Japan partnership in the 787 development. Following a long tradition of US-Japan Conference, we are now emphasizing the present cutting edge technology topics to promote more lively discussion. The following Special Sessions are being planned:

1. Nanocomposites: Modeling and Reality
2. Multiscale Modeling
3. Multifunctional Composites
4. Increased Fidelity in Composites Analysis and Design
5. Composite Affordability and Certification
6. Composite Durability
7. Structural Health Monitoring and Nondestructive Evaluation

General sessions are also planned on the following topics of interest:

**Materials:** Resin, Reinforcements and Preform, Textile Composites, Interface and Interphase, Metal Matrix Composites, Ceramic Matrix Composites, Thermoplastic Matrix Composites, Bio-composites

**Manufacturing:** RTM, VaRTM, Filament Winding, Prepreg, Pultrusion, Compression Molding, Curing Studies, Forming

**Property:** Test Methods, Impact, Energy Absorption, Fatigue, Creep, Vibration & Damping

**Mechanics:** Micromechanics, Modeling, Damage Mechanics, Design and Optimization, Joints

**Application:** Aircraft, Space, Automobile, Marine, Sports, Infrastructure, Energy, Electronics

**Life Cycle Assessment:** Environmental Impact, Life Cycle Costing, Recycling

**Conference Chairpersons**
Prof. Nobuo Takeda, University of Tokyo, Tokyo, Japan
Prof. R. Byron Pipes, Purdue University, West Lafayette, IN, USA

**Abstract Submission**
Abstracts (500-800 words) should be submitted electronically at usjapan2008@smart.k.u-tokyo.ac.jp.
**Important Dates**

- **January 10, 2008** (Extended) Deadline for abstract submission
- **February 1, 2008** (Extended) Notification of abstract acceptance
- **March 10, 2008** (Extended) Deadline for manuscript submission

**Registration Fees**

- Regular Fees: 30,000 Japanese Yen
- Student Fees: 20,000 Japanese Yen

The registration fee covers the symposium participation, a program, a CD-ROM Proceeding, coffee breaks, and a banquet ticket (on June 6 evening). Payment of the registration fee can be made by Credit Card. Please see our website for the details.

**Location**

The conference is held at Surugadai campus of College of Science and Technology, Nihon University. ([http://www.cst.nihon-u.ac.jp/english/life/c_map.html](http://www.cst.nihon-u.ac.jp/english/life/c_map.html)) The conference venue is just three minutes’ walk from JR Ochanomizu station, which is close to JR Tokyo station. List of recommended accommodation will provided in the website.

List of travel agents

- [http://www.nta.co.jp/english/](http://www.nta.co.jp/english/)
- [http://www.knt.co.jp/kokusai/index.html](http://www.knt.co.jp/kokusai/index.html)

**Conference website**  [www.smart.k.u-tokyo.ac.jp/usjapan2008](http://www.smart.k.u-tokyo.ac.jp/usjapan2008)

Contact e-mail address: [takeda@smart.k.u-tokyo.ac.jp](mailto:takeda@smart.k.u-tokyo.ac.jp) (Prof. Nobuo Takeda)